

## INTEGRATED CIRCUITS

# DATA SHEET

For a complete data sheet, please also download:

- The IC04 LOCMOS HE4000B Logic Family Specifications HEF, HEC
- The IC04 LOCMOS HE4000B Logic Package Outlines/Information HEF, HEC

**HEF4505B**  
**LSI**  
64-bit, 1-bit per word random  
access read/write memory

Product specification  
File under Integrated Circuits, IC04

January 1995

## 64-bit, 1-bit per word random access read/write memory

**HEF4505B**  
**LSI**

### DESCRIPTION

The HEF4505B is a 64-bit, 1-bit per word, fully decoded and completely static, random access memory. The memory is strobed for reading or writing only when the strobe input (ST), chip enable inputs (CE<sub>1</sub> and CE<sub>2</sub>) are HIGH simultaneously. The output data is available at the data output (D<sub>OUT</sub>) only when the memory is strobed, the read/write input (R/W) is HIGH and after the read access time has passed. Note that the three-state output is initially disabled and always goes to the LOW state before data is valid. The output is disabled in the high-impedance OFF-state, when the memory is not strobed or R/W is LOW. R/W may remain HIGH during a read cycle or LOW during a write cycle. The output data has the same polarity as the input data.

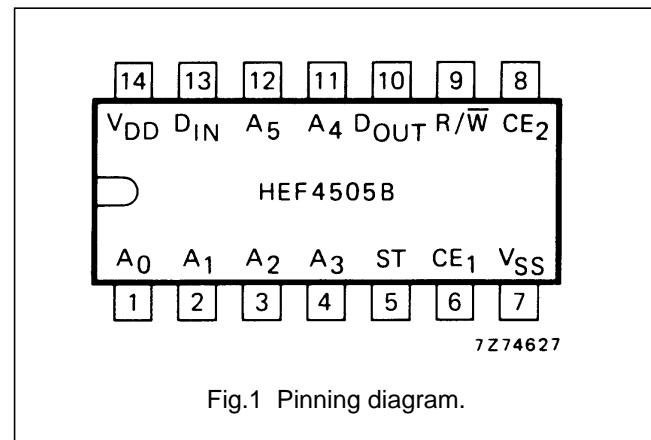


Fig.1 Pinning diagram.

HEF4505BP(N): 14-lead DIL; plastic  
(SOT27-1)

HEF4505BD(F): 14-lead DIL; ceramic (cerdip)  
(SOT73)

( ): Package Designator North America

### PINNING

A <sub>0</sub> to A <sub>5</sub>	address inputs
CE <sub>1</sub> , CE <sub>2</sub>	chip enable inputs
R/W	read/write input
ST	strobe input
D <sub>IN</sub>	data input
D <sub>OUT</sub>	data output

### FUNCTION TABLE

ST, CE <sub>1</sub> , CE <sub>2</sub>	R/W	D <sub>OUT</sub>	MODE
L	L	Z	disabled
H	L	Z	write
L	H	Z	disabled
H	H	equal to memory data	read

### Note

1. H = HIGH state (the more positive voltage)  
L = LOW state (the less positive voltage)  
Z = high-impedance OFF-state

### SUPPLY VOLTAGE

RATING	OPERATING
-0,5 to +15	4,5 to 15 V

### Note

1. Minimum standby voltage for data retention is 3 V.

### FAMILY DATA, I<sub>DD</sub> LIMITS category LSI

See Family Specifications

64-bit, 1-bit per word random access  
read/write memory

HEF4505B  
LSI

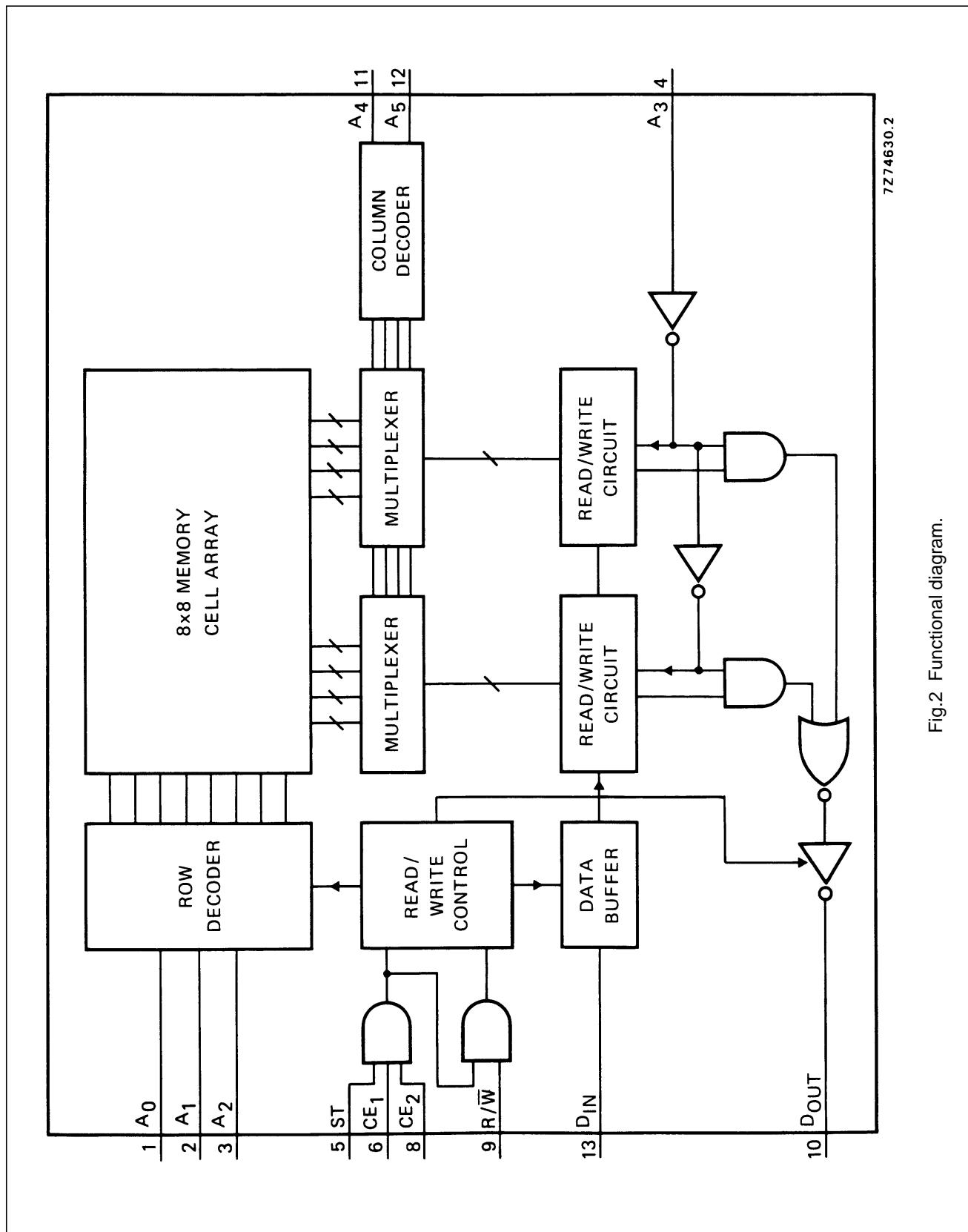


Fig.2 Functional diagram.

64-bit, 1-bit per word random access  
read/write memory

HEF4505B  
LSI

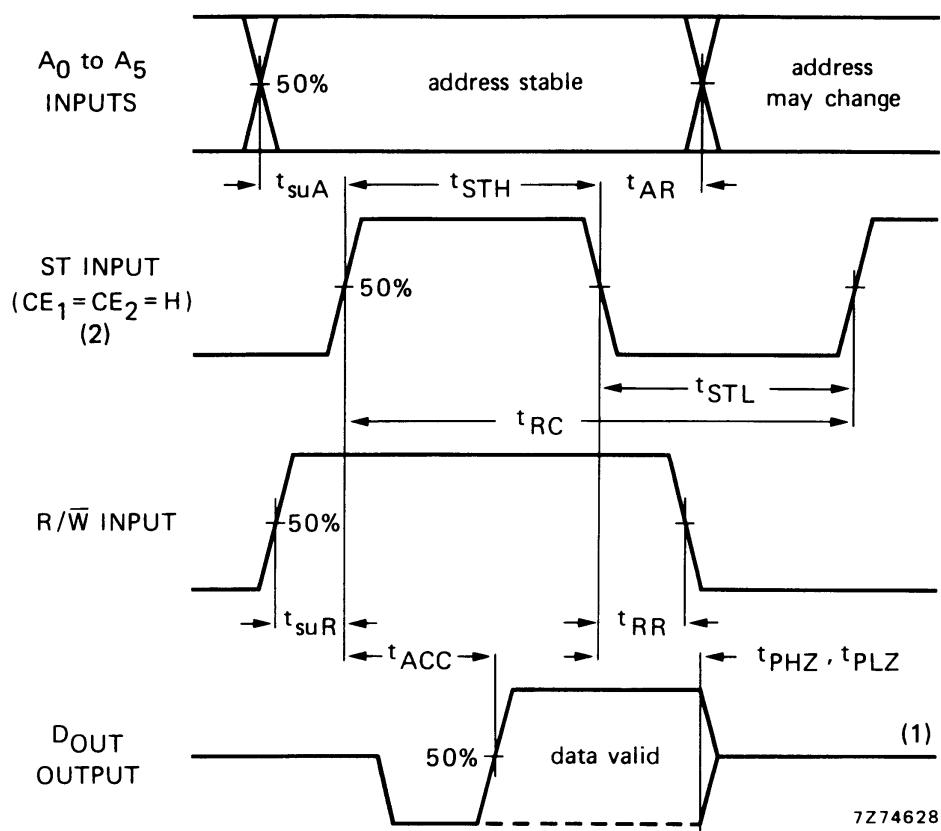
**AC CHARACTERISTICS**

$V_{SS} = 0$  V;  $T_{amb} = 25$  °C;  $C_L = 50$  pF; input transition times  $\leq 20$  ns

	$V_{DD}$ V	SYMBOL	MIN.	TYP.	MAX.	TYPICAL EXTRAPOLATION FORMULA
Minimum strobe pulse width; LOW	5	$t_{STL}$	75	35	ns	
	10		45	22	ns	
	15		30	15	ns	
Read cycle time	5	$t_{RC}$	350	700	ns	
	10		250	500	ns	
	15		210	420	ns	
Write cycle time	5	$t_{WC}$	220	440	ns	
	10		125	250	ns	
	15		75	150	ns	
Read access time	5	$t_{ACC}$	330	660	ns	303 ns + (0,55 ns/pF) $C_L$ 124 ns + (0,23 ns/pF) $C_L$ 92 ns + (0,16 ns/pF) $C_L$
	10		135	270	ns	
	15		100	200	ns	
Address recovery time	5	$t_{AR}$	80	40	ns	
	10		40	20	ns	
	15		25	10	ns	
Read recovery time	5	$t_{RR}$	180	90	ns	
	10		120	60	ns	
	15		90	45	ns	
Write recovery time	5	$t_{WR}$	75	35	ns	
	10		45	25	ns	
	15		40	20	ns	
3-state propagation delays	5		105	210	ns	
	10		60	125	ns	
	15		55	115	ns	
Output disable times	5	$t_{PHZ}, t_{PLZ}$	-20	-40	ns	
	10		-10	-20	ns	
	15		-5	-10	ns	
Set-up times $A_n \rightarrow ST$	5	$t_{suA}$	-30	-60	ns	
	10		-15	-30	ns	
	15		-5	-10	ns	
$R/\bar{W} \rightarrow ST$	5	$t_{suR}$	160	80	ns	
	10		75	35	ns	
	15		45	20	ns	
$D_{IN} \rightarrow ST$	5	$t_{suD}$	240	120	ns	
	10		100	50	ns	
	15		75	35	ns	
$R/\bar{W} \rightarrow ST$	5	$t_{suW}$	160	80	ns	
	10		75	35	ns	
	15		45	20	ns	

64-bit, 1-bit per word random access  
read/write memoryHEF4505B  
LSI

	$V_{DD}$ V	SYMBOL	MIN.	TYP.	MAX.	TYPICAL EXTRAPOLATION FORMULA
Hold time $D_{IN} \rightarrow ST$	5	$t_{holdD}$	-20	-40	ns	
	10		5	-10	ns	
	15		10	0	ns	



(1) Output in high impedance OFF-state.

(2) t<sub>STHmin</sub> = t<sub>RCmax</sub> - t<sub>STLmin</sub>.

Fig.3 Read cycle timing diagram.

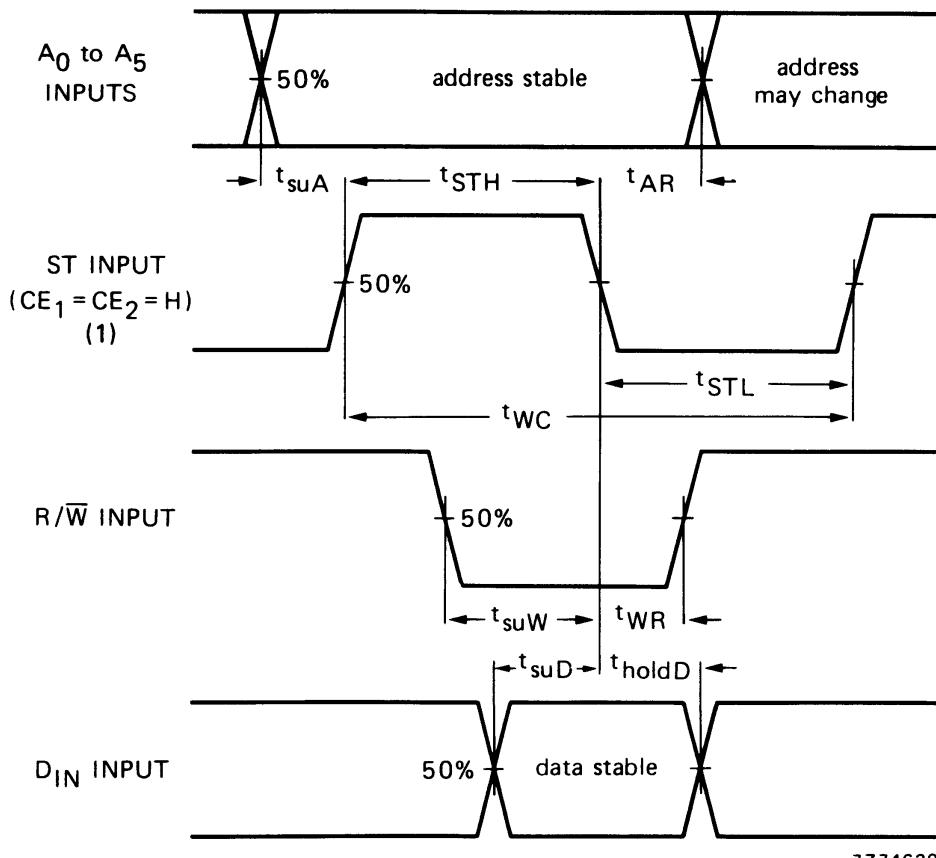
64-bit, 1-bit per word random access  
read/write memoryHEF4505B  
LSI(1) t<sub>STHmin</sub> = t<sub>WCmax</sub> - t<sub>STLmin</sub>.

Fig.4 Write cycle timing diagram.

64-bit, 1-bit per word random access  
read/write memory

HEF4505B  
LSI

APPLICATION INFORMATION

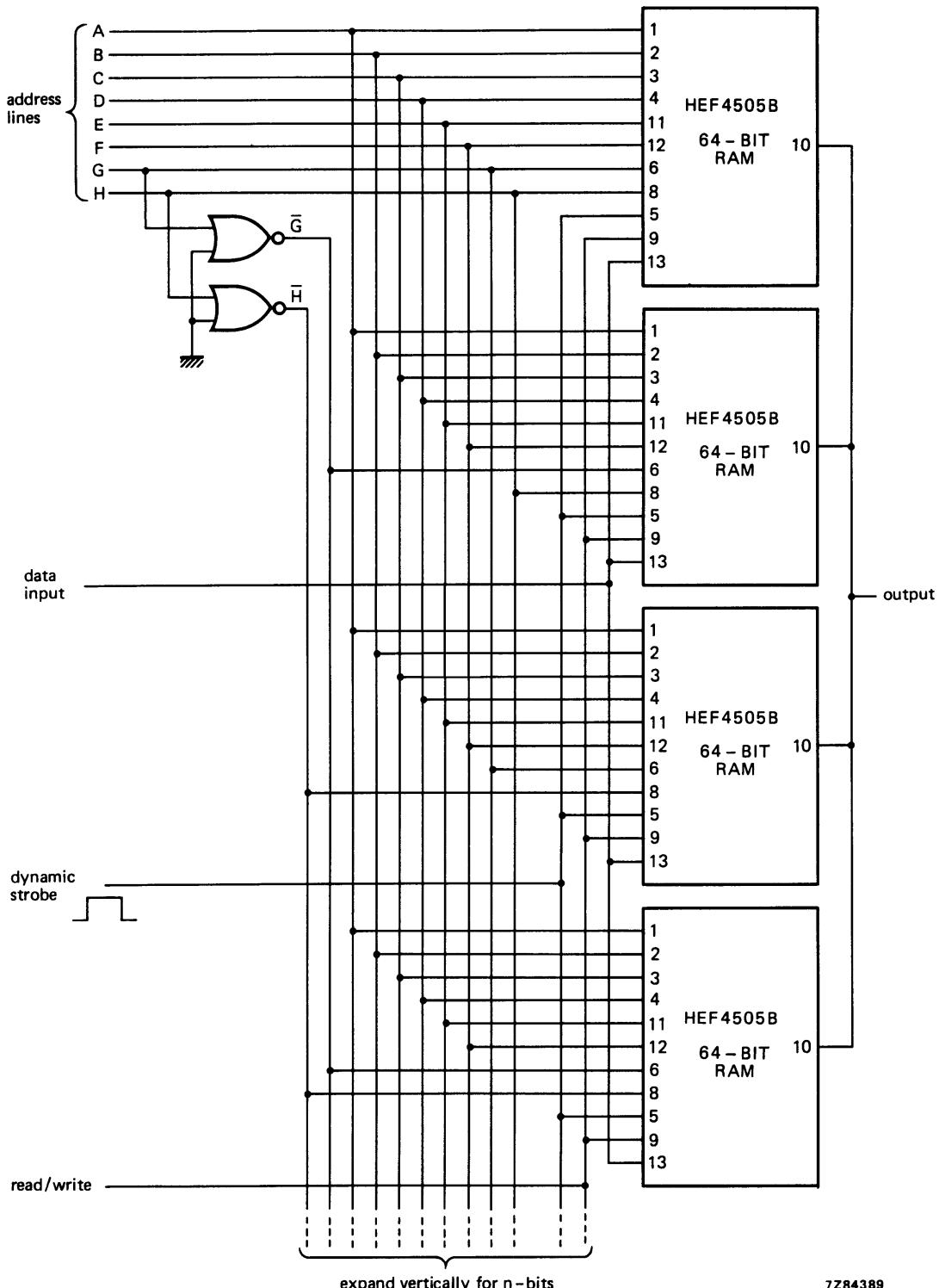


Fig.5 256-word by  $n$ -bit static read/write memory using HEF4505B ICs.

## 64-bit, 1-bit per word random access read/write memory

HEF4505B  
LSI

Figure 5 shows a 256-word by n-bit static RAM system. The outputs of the four HEF4505B circuits are tied together to form 256 words by 1-bit. Additional bits are attained by paralleling the inputs in groups of four. Memories of larger words can be attained by decoding the most significant bits of the address and AND-ing them with the strobe input.

Fan-in and fan-out of the memory are limited only by speed requirements. The extremely low input and output leakage currents keep the output voltage levels from changing significantly as more outputs are tied together. With the output levels independent of fan-out, most of the power supply range is available as logic swing, regardless of the number of units wired together. As a result, high noise immunity is maintained under all conditions.

The memory system shown in Fig.5 can be interfaced directly with other ICs of the LCMOS HE family. No external components are required.

Non-volatile information storage is allowed due to very low power dissipation when the memory is powered by a small standby battery. Figure 6 shows an optional standby power supply circuit for making a LCMOS memory 'non-volatile'. When the usual power fails, a battery is used to sustain operation or maintain stored information. While normal power supply voltage is present, the battery is trickle-charged through a resistor (R) which sets the charging rate. In Fig.6 the sustaining voltage is  $V_B$ , and  $+V$  is the ordinary voltage from a power supply.  $V_{DD}$  is connected to the power supply pin of the memory. Low-leakage diodes are recommended to conserve battery power.

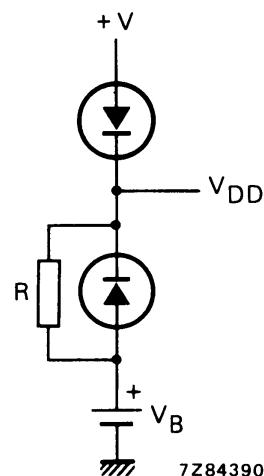


Fig.6 Standby battery circuit.